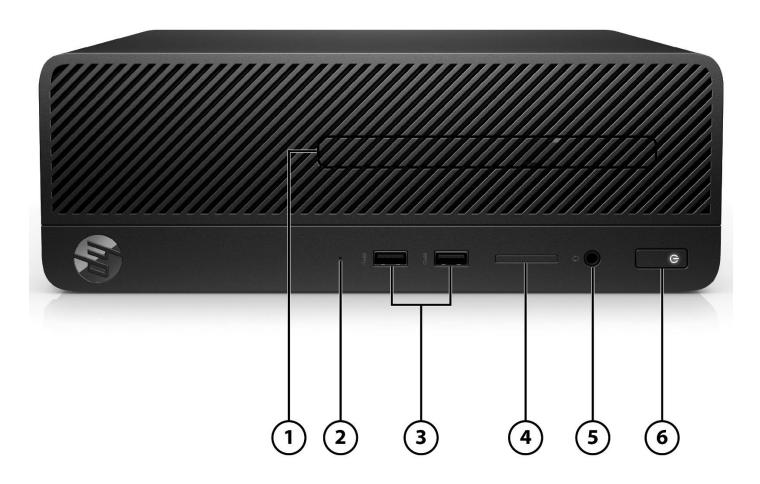
Overview

HP 290 G1 Small Form Factor Business PC



Front

- 1. Slim-height Bay supporting an optical disk drive (optional)
- 2. HDD LED light
- 3. (2) USB 3.1 Gen 1 Ports
- 4. SD Media Card Reader
- 5. Microphone/Headphone Combo Jack
- 6. Power Button

Not Shown

Slots (1

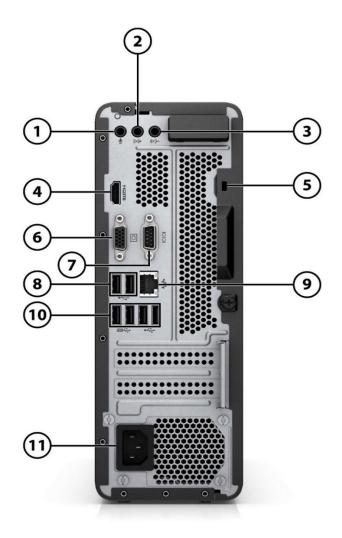
- (1) PCI Express x16
- (1) PCI Express x1
- (1) M.2 for WLAN
- (1) M.2 2242/2280 storage

Bays

- (1) 3.5" or 2.5" internal storage
- (1) Slim-height bay

Overview

HP 290 G1 Small Form Factor Business PC



Back

- 1. Audio Mic in
- 2. Audio Line out
- 3. Audio Link in
- 4. HDMI Port1
- 5. Standard lock slot
 - **Not Shown**

Optional Parallel Port (Optional via PCIex1 slot)
Optional 4 Serial Port (Optional via PCIe slot)

- 6. VGA Port1
- 7. Serial Port
- 8. (2) USB 2.0 port
- 9. RJ-45 Network Connector
- 10. (2) USB 3.1 Gen1 Port (left) and (2) USB 2.0 port (right)
- 11. Power Cord Connector

1. Port will be covered up when discrete graphic card is configured on shipped machine

At A Glance



Standard Features and Configurable Modules

At A Glance

- Windows 10 Pro, Windows 10 Home or FreeDos 2.0
- Intel® H370 chipset supporting Intel® 8th and 9th generation processors, featuring Intel® UHD Graphics
- Supports an optional discrete graphics card
- Integrated 10/100/1000 Ethernet Controller or 802.11a/b/g/n/ac (1x1) WiFi and Bluetooth® 4.2 Combo
- Up to 32GB DDR4-2666 Unbuffered Memory (UDIMM)
- Independent monitor support via VGA and HDMI interfaces
- TPM 2.0 support (firmware)*
- Supports both Hard Disk Drives and SATA TLC / M.2 PCIe NVMe Solid State Drives
- Audio in, Audio out and Mic in support 5.1 channel
- 8 USB Ports (including 4 USB 3.1 Gen1 ports)
- 180W Full range 115V/230V
- Security cable lock supported (sold separately)
- Protected by HP Services; terms and conditions vary by country; certain restrictions and exclusions apply
- Dust filter available

1. TPM feature will not be supported on machine pre-configured with FreeDOS, In some cases, machines pre-configured with Windows OS might ship with TPM turned off

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Standard Features and Configurable Modules

OPERATING SYSTEMS

Preinstalled (Windows)

Windows 10 Pro 64¹ Windows 10 Home 64¹

Pre-installed (Other)

FreeDOS 2.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.microsoft.com.

PROCESSORS

Intel® Celeron® Processors^{2,3}

CPU Intel Celeron G4900 Dual Core 3.1GHz 2400MHz 54W (3.1 GHz, 2 MB cache, 2 cores) CPU Intel Celeron G4930 Dual Core 3.2GHz 2400MHz 54W (3.2GHz, 2 MB cache, 2 cores)

Intel® Pentium Gold®2,3

CPU Intel Pentium G5400 Dual Core 3.7GHz 2400MHz 54W (3.7 GHz, 4 MB cache, 2 cores) CPU Intel Pentium G5420 Dual Core 3.8GHz 2400MHz 54W (3.8GHz, 4 MB cache, 2 cores) CPU Intel Pentium G5600 Dual Core 3.9GHz 2400MHz 54W (3.9 GHz, 4 MB cache, 2 cores) CPU Intel Pentium G5620 Dual Core 3.8GHz 2400MHz 54W (3.8GHz, 4 MB cache, 2 cores)

Intel 8th Processors Intel® Core™ i3^{2,3}

CPU Intel Core i3-8100 Quad Core 3.6GHz 2400MHz 65W (3.6 GHz, 6 MB cache, 4 cores)

Intel® Core™ i5^{2,3}

CPU Intel Core i5-8400 6C 2.8GHz 2666MHz 65W (2.8GHz, turbo up to 4GHz, 9 MB cache, 6 cores)

Intel® Core™ i5^{2,3}

CPU Intel Core i5-8500 6C 3.0GHz 2666MHz 65W (3GHz, turbo up to 4.1GHz, 9 MB cache, 6 cores)

Intel® Core™ i7^{2,3}

CPU Intel Core i7-8700 6C 3.2GHz 2666MHz 65W (3.2GHz, turbo up to 4.6GHz, 12 MB cache, 6 cores)

Intel 9th Processors Intel® Core™ i3^{2,3}

CPU Intel Core i3-9100 4C 3.6GHz 2400MHz 65W (3.6GHz, turbo up to 4.2GHz, 6 MB cache, 4 cores)

CPU Intel Core i3-9300 4C 3.7GHz 2400MHz 62W (3.7GHz, turbo up to 4.3GHz, 8 MB cache, 4 cores)

Intel® Core™ i5^{2,3}

CPU Intel Core i5-9400 6C 2.9GHz 2666MHz 65W (2.9GHz, turbo up to 4.1GHz, 9 MB cache, 6 cores)*



Standard Features and Configurable Modules

CPU Intel Core i5-9400F 6C 2.9GHz 2666MHz 65W (2.9GHz, turbo up to 4.1GHz, 9 MB cache, 6 cores)

CPU Intel Core i5-9500 6C 3GHz 2666MHz 65W (3GHz, turbo up to 4.4GHz, 9 MB cache, 6 cores)

CPU Intel Core i5-9500F 6C 3GHz 2666MHz 65W (3GHz, turbo up to 4.4GHz, 9 MB cache, 6 cores)

CPU Intel Core i5-9600 6C 3.1GHz 2666MHz 65W (3.1GHz, turbo up to 4.6GHz, 9 MB cache, 6 cores)

Intel® Core™ i7^{2,3}

CPU Intel Core i7-9700 8C 3GHz 2666MHz 65W (3GHz, turbo up to 4.7GHz, 12 MB cache, 8 cores)

- 2. Your product does not support Windows 8 or Windows 7, In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel 8th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com
- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- *NOTE: Only available on selected region

CHIPSET

Intel® H370 Chipset

GRAPHICS

Integrated4,5

Intel® UHD
Graphics 630 (integrated on 8th Core i7/i5/i3 processors and 9th i5 processors)
Intel® UHD
Graphics 610 (integrated on 8th and 9th Pentium and Celeron)

Discrete Graphics

AMD Radeon™ R7 430 2GB PCIe x16 GFX NVIDIA® GeForce® GT730 1GB GFX NVIDIA® GeForce® GT730 2GB GFX

- 4. HD content required to view HD images.
- 5. Integrated Intel software is available on select models only and requires separately purchased projector, tv or computer monitor with an integrated or external receiver. External receivers connect to the projector, tv or computer monitor via a standard VGA, HDMI cable, also sold separately.



Standard Features and Configurable Modules

MEMORY

Both slots are customer accessible / upgradeable, Supports Dual Channel Memory

Maximum # of Slots **Form Factor Type Small Form Factor** DDR4 2666 (Transfer rates up 32 GB capacity 2 DIMM⁶

to 2666 MT/s)

4 GB DDR4-2666 UDIMM (1x4GB)

8 GB DDR4-2666 UDIMM (1x8GB)

8 GB DDR4-2666 UDIMM (2x4GB)

16 GB DDR4-2666 UDIMM (1x16GB)

16 GB DDR4-2666 UDIMM (2x8GB)

6. Memory modules support data transfer rates up to 2666 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

STORAGE AND DRIVES

SATA3 - 3.5" or 2.5" 6Gb/s HDDs*

2TB 7200 RPM SATA Hard Disk Drive

1TB 7200 RPM SATA Hard Disk Drive

500GB 7200 RPM SATA Hard Disk Drive

128GB 2.5" TLC SSD

256GB 2.5" TLC SSD

M.2 Solid State Drives 7

128GB M.2 NVMe

256GB M.2 NVMe

512GB M.2 NVMe

SD Card Reader⁸

SD/SDHC/SDXC SD Card Reader

7. For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

8. Card sold separately.

OPTICAL DISC DRIVES

DVD-ROM 9.5mm⁹ DVD-Writer 9.5mm⁹



Standard Features and Configurable Modules

9. Optical drives are optional or add on features. Duplication of copyrighted material is strictly prohibited. Actual speeds may vary. Double Layer media compatibility will widely vary with some home DVD players and DVD-ROM drives.

NETWORKING/COMMUNICATIONS

Networking

Integrated 10/100/1000M GbE LAN

Wi-Fi and Bluetooth®10

802.11a/b/g/n/ac (1x1) WiFi and Bluetooth® 4.2 Combo

10. Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited.

AUDIO/MULTIMEDIA

Integrated Hi-Definition Audio
Combo Jack, Headphone/ Microphone
Line-in/ Line-out/ Mic-in jacks(3.5mm)

KEYBOARDS/POINTING DEVICES/BUTTONS AND FUNCTIONS KEYS

Keyboard

USB Business Slim Wired Keyboard HP USB Keyboard Business Slim USB Antimicrobial Wired Keyboard (China) No KB Option

Mouse

Antimicrobial USB Mouse (China) HP Optical USB Mouse Universal Wired Mouse USB USB Hardened Mouse (India) No Mouse Option

PORTS

Front

Slim-height Bay - supporting an optical disk drive (optional) HDD LED light (2) USB 3.1 Gen 1 Ports SD Media Card Reader



Standard Features and Configurable Modules

Microphone/Headphone Combo Jack Power Button

Not Shown

Slots (1) PCI Express x16

- (1) PCI Express x1
- (1) M.2 for WLAN
- (1) M.2 2242/2280 storage

Rear

Audio Mic in

Audio Line out

Audio Link in

HDMI Port1

Standard lock slot

VGA Port1

Serial Port

(2) USB 2.0 port

RJ-45 Network Connector

(2) USB 3.1 Gen1 Port and (2) USB 2.0 port

Power Cord Connector

Not Shown

Optional Parallel Port (Optional via PCIex1 slot)

1. Port will be covered up when discrete graphic card is configured on shipped machine

BAYS

- (1) 3.5" or 2.5" internal storage
- (1) Slim-height bay



Standard Features and Configurable Modules

ENVIRONMENTAL & INDUSTRY

ENVIKUNMENI						
Environmental Data	Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • EPEAT® registered in the United States.* See: http://www.epeat.net for registration status in your country.				
	System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".				
	Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC,	, 50Hz	100VAC, 60Hz	
	Normal Operation (Short idle)	10.93	11.1	6	10.96	
	Normal Operation (Long idle)	10.39	10.3	37	10.18	
1	Sleep	0.65	0.6	8	0.65	
	Off	0.36	0.3	9	0.37	
		Note: Energy efficiency da offered within the model f Logo are compliant with th	amily. HP comp	uters marked	with the ENERGY STAR®	
		(EPA) ENERGY STAR® spectoffer ENERGY STAR® complise for a typically configured supply, and a Microsoft Wi	ifications for co bliant configurat d PC featuring a	mputers. If a i tions, then en hard disk driv	model family does not ergy efficiency data listed	
	Heat Dissipation*	115VAC, 60Hz	230VAC,		100VAC, 60Hz	
	Normal Operation (Short idle)	37.27	38.0		37.37	
	Normal Operation (Long idle)	35.43	35.3	86	34.71	
	Sleep	2.22	2.3	2	2.22	
	Off	1.23	1.3	3	1.26	
		*NOTE: Heat dissipation is service level is attained fo		ed on the mea	sured watts, assuming the	
	Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power Sound Pressure (L _{WAd} , bels) (L _{pAm} , decibels)				
	Typically Configured – Idle	3.3		26		
	Fixed Disk – Random writes	3.4 26.1		26.1		
	Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:				
		Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.				
		years after the end of prod	duction.			
	Batteries		duction.			



Standard Features and Configurable Modules

	Batteries use	ed in the product do not contain:	
	Mercury greater the1ppm by weight		
	Cadmium greater than 20ppm by weight		
	Pattory size (P2022 (sein sell)		
	Battery size: CR2032 (coin cell) Battery type: Lithium		
Additional Information	• This product is in compliance with the Restrictions of Hazardous		
The state of the s		stances (RoHS) directive - 2011/65/EC.	,us
	• • Th	is HP product is designed to comply with the Waste Electric	al and
	Elec	tronic Equipment (WEEE) Directive – 2002/96/EC.	
		is product is in compliance with California Proposition 65 (S	
		fornia; Safe Drinking Water and Toxic Enforcement Act of 19 his product is in compliance with the IEEE 1680 (EPEAT) stan	
		Silver level, see www.epeat.net*	iudi u at
		astics parts weighing over 25 grams used in the product are	marked
	per ISO11469 and ISO1043.		
	This product contains 0% post-consumer recycled plastic (by wt.)		
	• • Th	is product is 94.4% recycle-able when properly disposed of	at end of
Packaging Materials	External:	PAPER/Corrugated	
- uckaying i laterials	Internal:	PLASTIC/EPE (Expanded Polyethylene)	
		PLASTIC/Polyethylene low density - LDPE	
		Paper/Molded pulp	
		packaging material contains at least 50% recycled content.	
	_	ited paper packaging materials contains at least 75% recycl	led
Material Usage	content.	does not contain any of the following substances in excess	of
riaterial usage		mits (refer to the HP General Specification for the Environm	
		hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf	
		estos	
		tain Azo Colorants tain Brominated Flame Retardants – may not be used as fla	mρ
		ardants in plastics	ille
		mium	
		orinated Hydrocarbons	
		orinated Paraffins	
		maldehyde ogenated Diphenyl Methanes	
		d carbonates and sulfates	
		d and Lead compounds	
		curic Oxide Batteries	
		kel – finishes must not be used on the external surface design	gned to
		requently handled or carried by the user.	
		ne Depleting Substances	
	-	ybrominated Biphenyls (PBBs) ybrominated Biphenyl Ethers (PBBEs)	
		ybrominated Biphenyl Oxides (PBBOs)	
	-	ychlorinated Biphenyl (PCB)	
	-	ychlorinated Terphenyls (PCT)	
		yvinyl Chloride (PVC) – except for wires and cables, has beer	ı
		untarily removed from most applications. ioactive Substances	



Standard Features and Configurable Modules

	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp- information/environment/ecolabels.html ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

*EPEAT® registered where applicable. EPEAT registration varies by country. See www.epeat.net for registration status by country



Standard Features and Configurable Modules

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Security and Protection

McAfee* LiveSafe™ 11

Productivity

Buy Office (sold separately) Dropbox¹²

ODD Playback and TV Tuners

Power Media Player 14 for HP with DVD (ODD SKU only)¹³

Movies

Netflix14

App Stores and Content Purchasing

Amazon¹⁴

HP Utilities and Support

HP Documentation

HP JumpStarts

HP Audio Switch¹⁵

HP Support Assistant¹⁶

BTB

HP Setup Integrated 00BE

Hardware Enabling Drivers or software utility

HP System Event Utility

*NOTE: Available for LA region only.

- 11. Free 1-year subscription of McAfee LiveSafe service included. Internet access required and not included. Subscription required after expiration 12. New Dropbox users are eligible to get 25 GB of Dropbox space free for 12 months from date of registration. For complete details and terms of use, including cancellation policies, visit the Dropbox website at https://www.dropbox.com/help/space/hp-promotion. Internet service required and not included.
- 13. Actual speeds may vary. Don't copy copyright-protected materials
- 14. Internet access required and not included.
- 15. Easily switch between speaker and microphone sources with intuitive controls and a consistent app experience
- 16. For more information visit hp.com/go/hpsupportassistant [Link will vary outside of the U.S.] HP Support Assistant is available for Android and Windows based PCs.

POWER

Power Supply

180 W

ENERGY® STAR® Libra2 EPA90 (Gold) Full range 115V/230V



Standard Features and Configurable Modules

WEIGHT AND DIMENSIONS

(configured with 1 HDD and 1 ODD)

Chassis (W x H x D) 3.74 x 10.63 x 11.65 in (95 x 270 x 296 mm)

System Weight 9.23 lbs / 4.2 kg*

*NOTE: Weight varies by configuration and component

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

Environmental and Industry

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 32° to 104° F (0° to 40° C)¹³

Non-operating: -22° to 140° F(-30° to 60° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 0% to 95% (non-condensing at ambient)

Maximum Altitude (unpressurized) Operating: 10,000 ft (3048 m)

Non-operating: 30,000 ft (9144 m)

13. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.



Standard Features and Configurable Modules

SERVICE AND SUPPORT

On-site Warranty¹⁴: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day¹⁵ service for parts and labor and complimentary limited technical support¹⁶. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack¹⁷. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

- 14. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 15. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 16. Technical support applies only to HP-configured and third-party HP qualified hardware and software.
- 17. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

ENERGY STAR® certified; EPEAT® registered

18. EPEAT® registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. See HP's 3rd party option store for solar energy accessory at http://www.hp.com/go/options.

GRAPHICS



Technical Specifications – Graphics

GRAPHICS

DisplayPort™	Multimode capable; supports HDCP, DisplayPort™ Audio (2 streams), HBR2 link rate Multi-Stream Technology for a maximum of 3 displays (including the integrated pa		
Maximum Graphics Memory	Microsoft Windows 7	Windows 8.1	Windows 10
	Up to 1.7GB	Up to 1.8GB	>4 GB
	Note: the actual amount of maximu depending upon your computer's co		nan the amounts listed above
Maximum Color Depth	32 bits/pixel		
Graphics/Video API Support	8th Generation Intel® Core™ pro	cessors:	
	 With Intel® UHD Graphics 630 DirectX 12, OpenGL 4.4, OpenCL 2.0, Intel® Quick Sync Video 		
	8th Generation Pentium® G5400 and Celeron® G4900		
	 With Intel® UHD Graphics 610 DirectX 12, OpenGL 4.4, OpenCL 2.0, Intel® Quick Sync Video 		
	•		: Video
	DirectX 12, OpenGL 4.4	, OpenCL 2.0, Intel® Quick Sync	: Video
Note: other resolutions m	DirectX 12, OpenGL 4.4 Supported Display Resolution	OpenCL 2.0, Intel® Quick Syncons	
Note: other resolutions m Resoluti	DirectX 12, OpenGL 4.4 Supported Display Resolutionary be available but are not recommend.	OpenCL 2.0, Intel® Quick Syncons	sted and qualified by HP
	DirectX 12, OpenGL 4.4 Supported Display Resolution ay be available but are not recommencion	OpenCL 2.0, Intel® Quick Sync ons and Refresh Rates led as they may not have been tes	sted and qualified by HP
Resoluti	DirectX 12, OpenGL 4.4 Supported Display Resolution ay be available but are not recommendion 00	OpenCL 2.0, Intel® Quick Sync ons and Refresh Rates led as they may not have been tes Refresh R	sted and qualified by HP Rates
Resoluti 800x60	DirectX 12, OpenGL 4.4 Supported Display Resolution ay be available but are not recommend ion 00 68	openCL 2.0, Intel® Quick Sync ons and Refresh Rates led as they may not have been tes Refresh R	sted and qualified by HP Rates Z
Resoluti 800×60 1024×7	DirectX 12, OpenGL 4.4 Supported Display Resolution ay be available but are not recommend ion 00 68 64	ons and Refresh Rates led as they may not have been tes Refresh R 60 Hz 60 Hz 60 Hz	sted and qualified by HP lates z z
Resoluti 800x60 1024x7 1152x8	Supported Display Resolutionay be available but are not recommendion 00 68 64	ons and Refresh Rates led as they may not have been tes Refresh R 60 Hz 60 Hz	sted and qualified by HP lates z z
Resoluti 800x60 1024x7 1152x8 1280x6	Supported Display Resolutionary be available but are not recommendation 00 68 64 00 20	ons and Refresh Rates led as they may not have been tes Refresh R 60 Hz 60 Hz 60 Hz	sted and qualified by HP Rates 2 2 2 2 2
Resoluti 800x60 1024x7 1152x8 1280x6 1280x7 1280x8 1280x9	Supported Display Resolutional by the available but are not recommendation of the supported Display Resolution of the supported Display Resolution of the support of the su	ons and Refresh Rates led as they may not have been tes Refresh R 60 Hz	sted and qualified by HP Rates Z Z Z Z Z
Resoluti 800x60 1024x7 1152x8 1280x6 1280x7 1280x8 1280x9	Supported Display Resolutionay be available but are not recommended by the second by t	ons and Refresh Rates ed as they may not have been tes Refresh R 60 Hz	sted and qualified by HP lates 2 2 2 2 2 2 2 2 2 2 2 2
Resoluti 800x60 1024x7 1152x8 1152x8 1280x7 1280x7 1280x9 1280x10 1360x7	Supported Display Resolutionay be available but are not recommended by the second by t	ons and Refresh Rates ed as they may not have been tes Refresh R 60 Hz	sted and qualified by HP Rates 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2
Resoluti 800x60 1024x7 1152x8 1152x8 1280x6 1280x7 1280x8 1280x9 1280x10 1360x7	Supported Display Resolutionary be available but are not recommendation 00 68 64 00 20 00 60 024 68 68	ons and Refresh Rates led as they may not have been tes Refresh R 60 Hz	sted and qualified by HP Rates Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z
Resoluti 800x60 1024x7 1152x8 1280x6 1280x7 1280x7 1280x8 1280x9 1280x10 1360x7 1366x7	Supported Display Resolutionay be available but are not recommended by the second by t	ons and Refresh Rates led as they may not have been tes Refresh R 60 Hz	sted and qualified by HP Rates Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z
Resoluti 800x60 1024x7 1152x8 1280x6 1280x7 1280x8 1280x9 1280x10 1366x7 1400x10	Supported Display Resolutionay be available but are not recommended by the second by t	ons and Refresh Rates led as they may not have been tes Refresh R 60 Hz	sted and qualified by HP Rates 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2
Resoluti 800x60 1024x7 1152x8 1152x8 1280x7 1280x8 1280x9 1280x10 1360x7 1366x7 1440x90 1600x9	Supported Display Resolutionay be available but are not recommended by the second but are not recommended by	ons and Refresh Rates led as they may not have been tess Refresh R 60 Hz	sted and qualified by HP Rates 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2
Resoluti 800x60 1024x7 1152x8 1280x6 1280x7 1280x8 1280x9 1280x10 1366x7 1440x9	Supported Display Resolutional be available but are not recommended ion DO 68 64 00 20 00 68 68 68 68 050 00 00 00 00 00 00 00 00	ons and Refresh Rates led as they may not have been tes Refresh R 60 Hz	sted and qualified by HP Rates 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2

* Only supported on displays connected to the external DisplayPort connector.

Technical Specifications – Graphics

NVIDIA® GeForce® GT 730 1GB Graphics Card

Engine Clock902 MHzMemory Clock1250 MHzMemory Size(width)1GB(64-bit)

 Memory Type
 128M x 32 GDDR5 @2pcs

 Max. Resolution(DVI)
 2560x1600@60Hz

 Max. Resolution(HDMI)
 4096x2160@24Hz

Multi Display Support 2 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) DVI+HDMI

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <35W

PCB form-factor with bracket LP PCB with FH/LP bracket

NVIDIA® GeForce® GT 730 2GB Graphics Card

Engine Clock 902 MHz
Memory Clock 1250 MHz
Memory Size(width) 2GB(64-bit)

 Memory Type
 256M x 32 GDDR5 @2pcs

 Max. Resolution(DVI)
 2560x1600@60Hz

 Max. Resolution(HDMI)
 4096x2160@60Hz

Multi Display Support 2 displays
HDCP Compliance Yes

Rear I/O connectors(bracket) DVI+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <35W

PCB form-factor with bracket LP PCB with FH/LP bracket



Technical Specifications – Graphics

AMD Radeon™ R7 430 2GB Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)2GB(128-bit)

Memory Type 128M x 32 GDDR5 @4pcs

Max. Resolution(VGA) 2048x1536

Max. Resolution(DP) 4096x2160@60Hz

Multi Display Support 2 displays

HDCP Compliance Yes
Rear I/O connectors(bracket) VGA+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket



Technical Specifications – Hard Disk and Solid State Storage

STORAGE

HP 2 TB* 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive*

Capacity2 TBRotational Speed7,200 rpmInterfaceSATA 6Gb/s NCQ

Buffer Size 64 MB

 Logical Blocks
 3,907,029,168

 Seek Time
 Read: <8.5 ms</td>

Write: < 9.5 ms

Height 1.028 in/26.11 mm **Width** 4.0 in/101.6 mm

Operating Temperature 32° to 140° F (0° to 60° C)

*NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows 7) and 36 GB (for Windows 8.1/10) of system disk is reserved for the system recovery software.

1TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 1 TB

Rotational Speed 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

Buffer Size 32 MB

 Logical Blocks
 1,953,525,168

 Seek Time
 Read: <8.5 ms</td>

 Write: <9.5 ms</td>

Full-Stroke: 21 ms

Height 1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

*NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows 10) of system disk is reserved for the system recovery software.

500GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 500 GB
Rotational Speed 7,200 rpm

Drive Type Serial ATA 3.0 (6.0 Gb/s)

 Interface
 32 MB

 Buffer Size
 976,773,168



Technical Specifications – Hard Disk and Solid State Storage

Seek Time Single Track: 2.0 ms

> Average: 11 ms Full-Stroke: 21 ms

Height 1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

*NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 9.5mm Desktop G2 Slim DVD Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g) **Read Speeds** DVD-R DL - Up to 6X DVD+R - Up to 8X

DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X

DVD-RW, DVD+RW - Up to 8X DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X

DVD-ROM DL, DVD-ROM - Up to 8X

CD-ROM, CD-R - Up to 24X CD-RW - Up to 24X

Access time

(typical reads, including settling)

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Stop Time 6 seconds (typical)

Power Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions Temperature 41° to 122° F (5° to 50° C) (operating - non-condensing)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Desktop G2 Slim DVD-ROM Drive

Height 9.5 mm height

Orientation Either horizontal or vertical



Technical Specifications – Hard Disk and Solid State Storage

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g)

Read Speeds DVD-R DL - Up to 6X

DVD+R - Up to 8X DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X

DVD-RW, DVD+RW - Up to 8X DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X

DVD-ROM DL, DVD-ROM - Up to 8X

CD-ROM, CD-R - Up to 24X CD-RW - Up to 24X

Dondon DVD

Access time Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) (typical reads, including Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

settling) Stop Time 6 seconds (typical)

Power Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions Temperature 41° to 122° F (5° to 50° C)

(operating - non-condensing) Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

128 GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10g
Capacity 128GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen3
Maximum Sequential Read Up to 1400MB/s

Maximum Sequential Write Up to 395MB/s
Logical Blocks 250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications – Hard Disk and Solid State Storage

256 GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</td>Capacity256 GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 780MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</th>Capacity512 GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 860MB/sLogical Blocks1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128GB 2.5in SATA Three Layer Cell SSD

Drive Weight <50g
Capacity 128GB
Height 7mm
Length 100.45mm
Width 69.85mm
Interface SATA 3.0 (6Gb/s)

Performance Up to Random Read/Write = 70K/40K IOPS



Technical Specifications – Hard Disk and Solid State Storage

Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 380MB/sLogical Blocks250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM; TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB 2.5in SATA Three Layer Cell SSD

Drive Weight <62g
Capacity 256GB
Height 7mm
Length 100.45mm
Width 69.85mm

Interface SATA 3.0 (6Gb/s)

Performance Up to Random Read/Write = 55K/68K IOPS

Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 450MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM; TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications - Audio

AUDIO

Audio control

Front side Combo jack for supporing CTIA, Rear side Line-in/Line-out/Mic-in jacks

High Definition Audio

Type Integrated

HD Audio Codec Realtek ALC3601

Audio I/O Ports Front side Combo jack for supporing CTIA, Rear side Line-in/ Line-out/ Mic-in jacks

Wavetable Syntheses Yes
Analog Audio Yes
Internal Speaker NA

DAC Sampling Rates 16 to 24-bit; 44.1K/ 48 K/96K / 192K Hz

ADC Sampling Rates 16 bit, 44.1K/ 48K/ 96K/ 192K Hz



Technical Specifications – Power

POWER SUPPLY

Operating Voltage Range 90 - 264 VAC Rated Voltage Range 100-240V AC 50/60 HZ **Rated Line Frequency Operating Line Frequency** 47 - 63 Hz**Rated Input Current** 180W: < 2.3A

Rated Input Current with Energy Efficient* Power

Supply 88/91/88% efficient at 20/50/100% load (230V)

DC Output +12.1V

Current Leakage (NFPA 99: Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as 2102)

required for Non-patient Electrical Appliances and Equipment used in a patient care facility or

that contact patients in normal use. Per section 10.3.5.1.

Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care

facility or that contact patients in normal use. Per section 10.3.5.1.

Power Supply Fan 50*20mm (linear type)



Technical Specifications – Weights and Dimensions

WEIGHTS AND DIMENSIONS

Chassis (W x H x D) 3.74 x 10.63 x 11.65 in (95 x 270 x 296 mm)

System Volume 463.16cu in

7.6L

System Weight* 9.23 lbs / 4.2 kg

Tower Stand 10.73 x 3.74 x 11.65 in (272.6 x 95 x 296 mm)

(H x W x D)

Packaged 13.46 x 7.72 x 19.65 in (**H x W x D**) 342 x 196 x 499 mm

Shipping Weight* 13.2 lb / 6 kg **Shipping Weight** 13.86 lb / 6.3 kg

(Molded Pulp)*

Palletization12-units per layerProfile6 layer max

72 per pallet

Footprint (H x W x D) 85.91 x 39.37 x 47.24 in (2182 x 1000 x 1200 mm)

*NOTE: Weight varies by configuration and component

Technical Specifications – Miscellaneous Features

ADDITIONAL FEATURES

Description

SMART Technology (Self-Monitoring, Analysis and Reporting Technology)

Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted



Technical Specifications - Networking

NETWORKING

10/100/1000 Integrated NIC

Ethernet Features 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s

Power Management ACPI compliant – multiple power modes

Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power consumption

Performance Features TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

Manageability Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up

Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Realtek 802.11ac (1x1) WiFi and Bluetooth® 4.2 Combo *

Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac	
Interoperability	Wi-Fi certified	
Frequency Bands	802.11b/g/n	•2.402 – 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
	802.11a/n	•4.9 – 4.95 GHz (Japan) •5.15 – 5.25 GHz •5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850
Data Rates	• 802.11g: 6• 802.11a: 6	, 2, 5.5, 11 Mbps , 9, 12, 18, 24, 36, 48, 54 Mbps , 9, 12, 18, 24, 36, 48, 54 Mbps ICS 0 ~ MCS 15, (20MHz, and 40MHz)



Technical Specifications - Networking

	• •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹	 • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI
	¹ Check latest software/driver release for updates on supported security features.
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming ²	IEEE 802.11 compliant roaming between access points
Output Power ²	 802.11b: +14dBm minimum 802.11g: +12dBm minimum 802.11a: +12dBm minimum 802.11n HT20(2.4GHz): +12dBm minimum 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +10dBm minimum 802.11n HT40(5GHz): +10dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum
Power Consumption	•Transmit mode2.0 W •Receive mode1.6 W •Idle mode (PSP)180 mW(WLAN Associated) •Idle mode50 mW(WLAN unassociated) •Connected Standby 10mW •Radio disabled8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum



Technical Specifications - Networking

	802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 3 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).		
Antenna type	High efficiency antenna. One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230 : 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating: 14° to 158° F (-10° to 70° C) Non-operating: -40° to 176° F (-40° to 80° C)		
Humidity	Operating: Non-operating:	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		

5. Wireless access point and Internet service required and not included. Availability of public wireless access points limited.



Technical Specifications - Networking

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channel Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-EV5)	
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Receiver Sensitivity Legacy	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Range	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Electrical Interface	USB 2.0 compliant
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support
Certifications Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2
	Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)



After Market Options

AFTER MARKET OPTIONS

<u>Type</u>	<u>Description</u>	<u> Part #</u>
Memory	HP 4GB DDR4-2666 DIMM	3TK85AA
	HP 8GB DDR4-2666 DIMM	3TK87AA
	HP 16GB DDR4-2666 DIMM	3TK83AA
Storage	HP 500GB SATA 6.0Gb/s Hard Drive	QK554AA
	HP 1TB 7200rpm SATA 6Gbps Hard Drive	QK555AA
	HP Turbo Drive Gen2 256GB M.2 SSD Drive	1CA51AA
	HP 256GB SATA TLC Non-SED Solid State Drive	P1N68AA
	HP 9.5mm G3 8/6/4 SFF G4 400 SFF/MT DVD Writer	1CA53AA
Graphics	Nvidia® GT 730 2GB DP Card	Z9H51AA
	AMD Radeon™ R7 430 Card	1MX32AA
Security	HP Business PC Security Lock V2 Kit	N3R93AA
	HP Keyed Cable Lock 10mm kit	T1A62AA
Adapters	HP PCIe x1 Parallel Port Card	N1M40AA
	HP HDMI Standard Cable Kit	T6F94AA
	HP USB to Serial Port Adapter	J7B60AA
Networking	Intel Ethernet I210-T1 GbE NIC Card	E0X95AA
Input	HP USB Mouse	QY777AA
	HP USB Hardened Mouse	P1N77AA
	HP USB Keyboard	QY776AA
	HP USB Business Slim Keyboard	N3R87AA
	HP Conferencing Keyboard	K8P74AA
	HP USB Antimicrobial Slim Keyboard and Mouse	Z9H50AA
Others	HP Business Headset v2	T4E61AA
	HP USB Business Speakers v2	N3R89AA



Change Log

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Date of change:	Version History:		Description of change:
March 18, 2019	From v1 to v2	Update	Processor i5-9400 removed
March 21, 2019	From v2 to v3	Update	Processor i5-9400 put back on
April 23, 2019	From v3 to v4	Refresh	Processors under embargo added to official QS refresh
May 14, 2019	From v4 to v5	Update	i7-9700/i5-9400F/i5-9500F added to processors
July 2, 2019	From v5 to v6	Update	CPU Intel Core i3-9300, i5-9600 and Pentium gold G5620 added and
			Intel® Core™ i7-9700 removed to/from processors section
August 1, 2019	From v6 to v7	Update	Pentium G5600 added to processors section
August 16, 2019	From v7 to v8	Update	Security Lock Slot upgraded to Standard
August 21, 2019	From v8 to v9	Update	Intel® Core™ i7-9700 put back in to processors section
October 3, 2019	From v9 to v10	Update	Miscellaneous features section added
March 4, 2020	From v10 to v11	Update	Intel® Core™ i7-9700 tech specs corrected

